AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

1. (Previously Presented) A method for the removal of one or more metal impurities in chloride-based copper recovery processes, comprising:

contacting an aqueous strong chloride solution, having an acidic or neutral pH of at least 6 and an alkali chloride content of at least 200 g/l, and comprising monovalent copper and one or more metal impurities with a chelating ion-exchange resin under conditions that:

bind one or more metal impurities to said chelating ion-exchange resin, and

do not bind at least some of said monovalent copper to said chelating ion-exchange resin,

thereby forming:

a bound chelating ion-exchange resin, and

a metal impurity depleted aqueous strong chloride solution comprising monovalent copper; and

separating said bound chelating ion-exchange resin from said metal impurity depleted aqueous strong chloride solution comprising monovalent copper.

2. (Previously Presented) A method according to claim 1, wherein the chelating ion-exchange resin has a styrene-divinyl-benzene matrix ring structure.

3. (Previously Presented) A method according to claim 1, wherein the chelating ion-exchange resin contains an iminodiacetic acid functional group.

4. (Previously Presented) A method according to claim 1, wherein the chelating ion-exchange resin contains an aminophosphonic functional group.

5. (Previously Presented) A method according to claim 1, wherein the one or more metal impurities contain zinc, nickel, lead, iron, manganese, or combinations of these.

6. (Canceled)

7. (Canceled)

8. (Previously Presented) A method according to claim 1, wherein the contacting occurs in an acidic environment.

9. (Previously Presented) A method according to claim 1, wherein the contacting occurs in a neutral environment.

10. (Previously Presented) A method according to claim 1, further comprising:

displacing a residual metal impurity depleted aqueous strong chloride solution comprising monovalent copper from the bound chelating ion-exchange resin by contacting the bound chelating ion-exchange resin with an NaCl solution;

eluting said one or more metal impurities from the bound chelating ion-exchange resin to form an eluted chelating ion-exchange resin;

regenerating the eluted chelating ion-exchange resin by contacting it with an alkaline solution; and

displacing the alkaline solution from the chelating ion-exchange resin with an NaCl solution before contacting the chelating ion-exchange resin with an aqueous strong chloride solution comprising monovalent copper and one or more metal impurities.

11. (Previously Presented) A method according to claim 1, further comprising removing the majority of the one or more metal impurities in the strong chloride solution of monovalent copper by hydroxide precipitation prior to the contacting with the chelating ion-exchange resin.

12. (Previously Presented) A method according to claim 11, wherein the hydroxide precipitation removes said one or more metal impurities to a content of 0.1 - 1 g/l.

13. (Previously Presented) A method according to claim 1, wherein said one or more metal impurities are removed from said aqueous strong chloride solution comprising monovalent copper and one or more metal impurities to at least a level that corresponds to cathode copper LME-A grade impurity level.

14. (Canceled)

15. (Currently Amended) A method for the removal of one or more metal impurities in chloride-based copper recovery processes, comprising:

contacting an aqueous strong chloride solution, having an acidic or neutral pH of at least 6 and an alkali chloride content of at least 200 g/l, ~~A method according to claim 1~~, wherein said aqueous strong chloride solution ~~comprising~~ comprises monovalent copper and one or more metal impurities and has a monovalent copper content of 30 - 100 g/l with a chelating ion-exchange resin under conditions that:

bind one or more metal impurities to said chelating ion-exchange resin, and

do not bind at least some of said monovalent copper to said chelating ion-exchange resin,

thereby forming:

a bound chelating ion-exchange resin, and

a metal impurity depleted aqueous strong chloride solution comprising monovalent copper; and

separating said bound chelating ion-exchange resin from said metal impurity depleted aqueous strong chloride solution comprising monovalent copper.